

Supporting Information

Facile patterning of amorphous indium oxide thin films based on gel-like aqueous precursor for low-temperature, high-performance thin-film transistors

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RMS roughness is defined as:

$$RMS = \sqrt{\frac{\sum_{i=1}^n (x_i - \bar{x})^2}{n}}$$

where x_i is surface height of every measured point, \bar{x} is average height, and n is the total number of measured points.

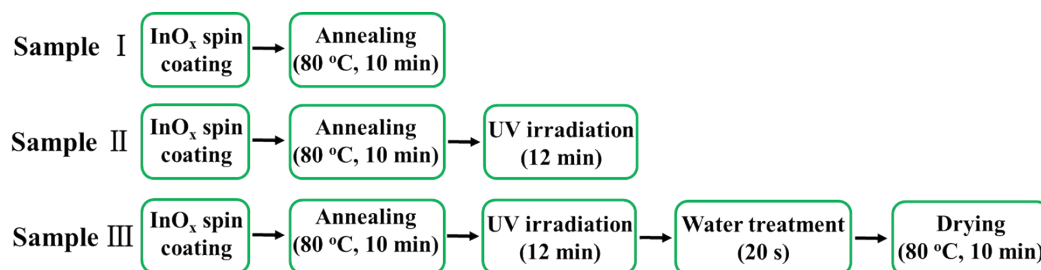


Figure S1. Preparation process-flow of samples.

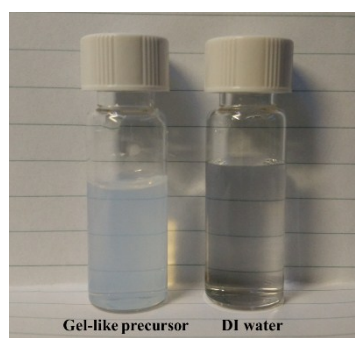


Figure S2. Optical image of gel-like aqueous precursor after filtering with 0.45 μm syringe filter.

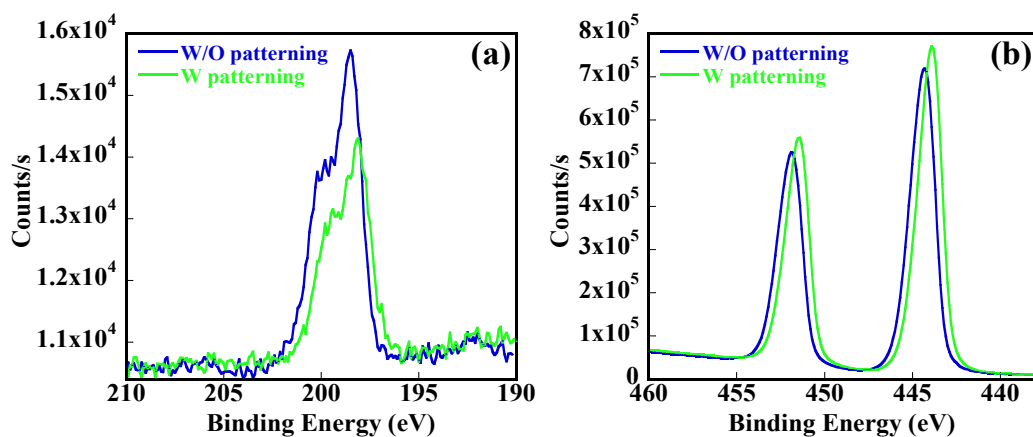


Figure S3. (a) Cl 2p and (b) In 3d XPS spectra collected from InO_x films annealed at 280 °C with and without UV irradiation and water treatment.

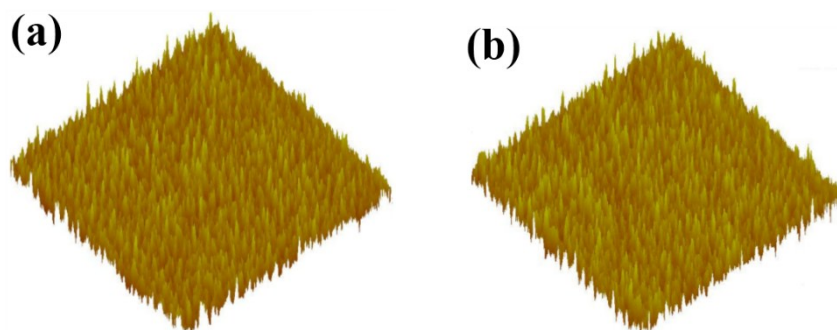


Figure S4. AFM images ($5 \mu\text{m} \times 5 \mu\text{m}$) of InO_x film (a) with and (b) without UV irradiation and water treatment.

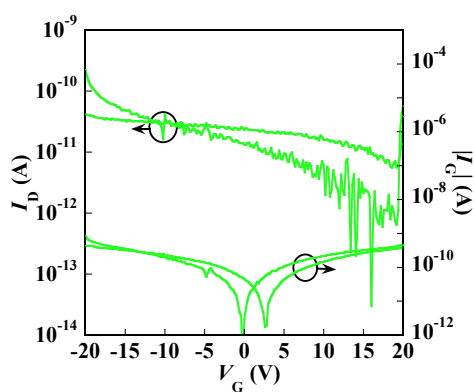


Figure S5. Transfer curves of InO_x TFT without UV irradiation and water treatment post-annealed at 180 °C.

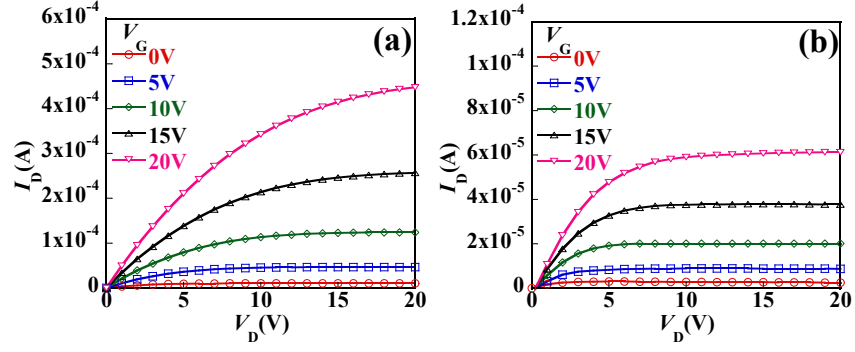


Figure S6. Output characteristics of InO_x TFTs (a) with and (b) without patterning, both devices were post-annealed at 280 °C.

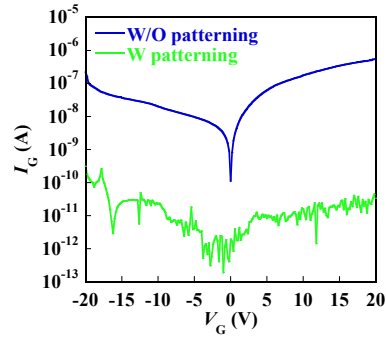


Figure S7. Gate leakage current (I_G) of InO_x TFTs with and without patterning, both devices were post-annealed at 280 °C.

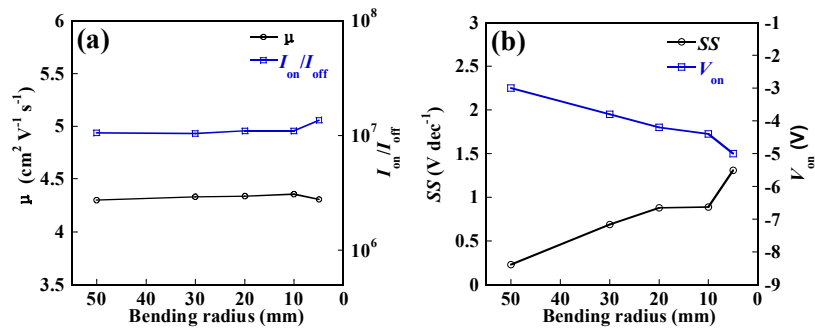


Figure S8. (a) μ and I_{on}/I_{off} , (b) SS and V_{on} variations of InO_x TFT with different bending radius.

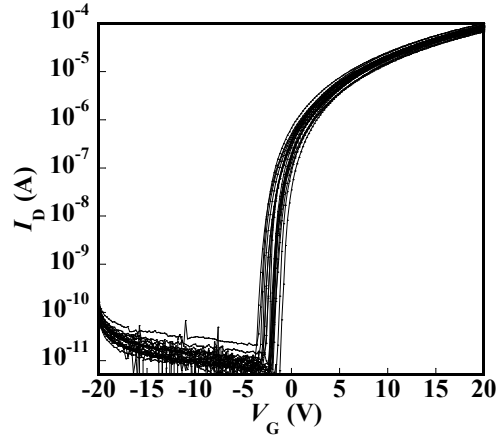


Figure S9. Transfer curves of 20 flexible InO_x TFTs.

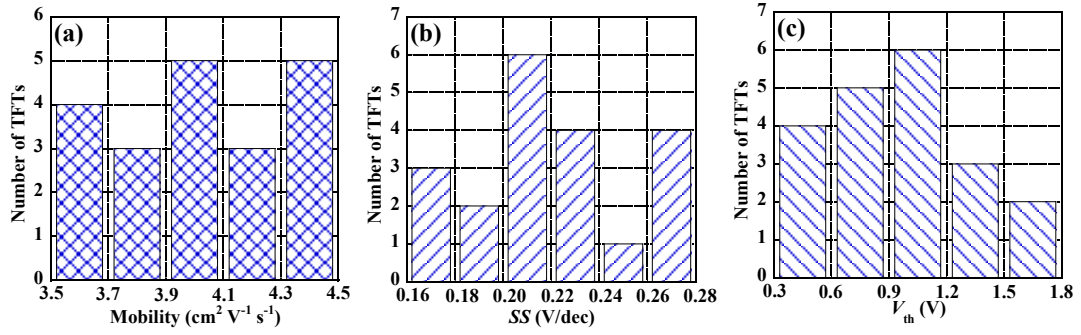


Figure S10. Statistical distributions of (a) mobilities, (b) subthreshold slopes, and (c) threshold voltages of 20 flexible InO_x TFTs.

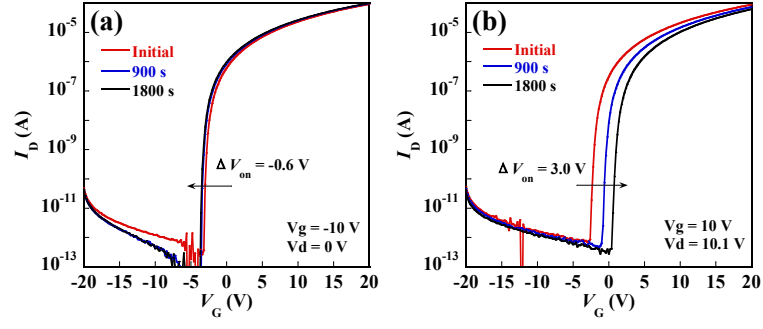


Figure S11. Variations of transfer curves under (a) negative and (b) positive gate bias stress.

Table S1. Comparison of this work to previous InO_x TFTs annealed at 200 °C

| | Precursor | Mobility (cm ² V ⁻¹ s ⁻¹) | SS (V/dec) | I _{on} /I _{off} | V _{th} (V) |
|-----------|-----------------------------------|--|------------|-----------------------------------|---------------------|
| This work | InCl ₃ | 3.3 | 0.3 | 2.6 × 10 ⁷ | 2.9 |
| Ref. 16 | In(NO ₃) ₃ | 3.14 | 0.16 | >10 ⁹ | ~0 |
| Ref. 25 | In(NO ₃) ₃ | 0.03 | - | 2.2 × 10 ⁴ | 1.5 |
| Ref. 36 | In(NO ₃) ₃ | 1.83 | 0.3 | ~10 ⁸ | -1.9 |
| Ref. 37 | In(NO ₃) ₃ | 1.44 | - | ~10 ⁶ | 9.6 |